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(54) Title: WATER-ABSORBENT RESIN COMPOSITION AND METHOD FOR PRODUCING THEREOF, AND ABSORBENT MATERIAL AND ABSORBENT PRODUCT USING THEREOF

(57) Abstract: A water-absorbent resin composition suffering exfoliation of additives from a water-absorbent resin only insignificantly and excelling in fluidity of powder after absorption of moisture and in deodorizing property and absorbent property as well is provided. The water-absorbent resin composition of this invention comprises water-absorbent resin obtainable by polymerizing an unsaturated monomer having an acid group and/or a salt thereof; and complex oxide hydrate containing zinc and silicon, or zinc and aluminum, wherein the complex oxide hydrate contains zinc as main metal component, the mass ratio of the content of zinc and the content of silicon or aluminum is in the range of 50/50 - 99/1, and the absorption capacity at 60 minutes toward 0.90 mass% sodium chloride aqueous solution under the pressure of 1.9 kPa is not less than 20 g/g.



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